

Post-Reflow  
Soldering System

# TAKU-ROBO

Bench Top Selective  
Soldering System



Compact, easy to program fountain type selective soldering system for high mix/low volume, prototyping, and de-mounting components. Taku Robo is a semi automatic selective soldering system developed for high mix/low volume and prototyping applications. The PCB is held using an edge rail frame, and programs can be generated manually or using Gerber and other data. Up to 100 points can be programmed. Pre-heat dwell time using Nitrogen and X, Y, and Z axis coordinates can be set precisely. Solder fillet quality is excellent.

- . **LOW COST**
- . **NITROGEN ATMOSPHERE**
- . **SIMPLE PROGRAMMING USING WINDOWS OR X/Y DRIVE**
- . **UNIVERSAL PANEL CAPABILITY – NO FIXTURES REQUIRED**
- . **PRECISE CONTROL OVER ALL SOLDERING PARAMETERS**
- . **APPLICABLE FOR LEAD FREE OR STANDARD APPLICATIONS**
- . **RAPID SET UP & CYCLE TIME**

## SPECIFICATIONS:

PCB Size (Minimum)	50mm x 50mm (1.96" x 1.96")
PCB Size (Maximum)	250mm x 330mm (9.85" x 13")
PCB Thickness	0.8 – 2.0mm ( .030" - .070")
Program Steps:	Up To 100
Solder Nozzle Diameter	3.0 – 10.0mm (.118" - .393")
Solder Pot Capacity	8.0Kg (17.6 lbs.)
N2 Supply	1-2 cfm
Power	208 Volts, 60 Hz, 3 Phase, 17 KVA
External Dimensions	600mm w (23.6") x 600mm d (23.6") x 350mm h (13.8")